

**Specifications** 

Insulation Resistance



ESD SMD Comm COG, Ceramic, 6,800 pF, 1%, 250 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206, 1.5 mm



General Information	
Generalinomation	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm
В	0.6mm +/-0.25mm

Capacitance	6,800 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	1%
Voltage DC	250 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	606
remp. Coemicient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Capacitance Change with Reference to +25°C and 0 VDC	

100 GOhms

Packaging Specifications	
Packaging	Bulk, Bag
Packaging Quantity	1

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 07/16/2025 © 2006 - 2025 YAGEO